

DIFFERENTIAL PAIR ARRAY DPAF SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?DPAF

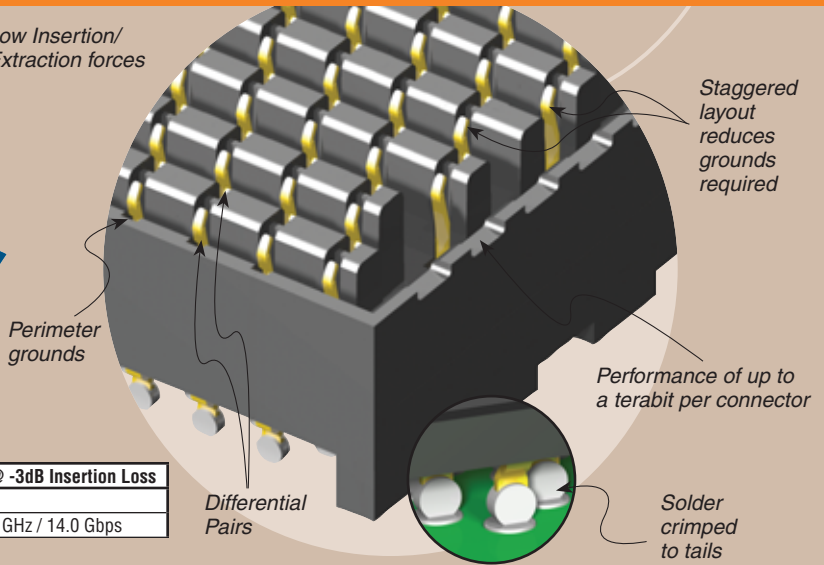
- Insulator Material:** Black Liquid Crystal Polymer
- Contact Material:** Copper Alloy
- Plating:** Au over 50µ" (1,27µm) Ni
- Current Rating (2x3):** 2.9A @ 30°C Temperature Rise
- Operating Temp Range:** -55°C to +125°C
- Contact Resistance:** 10.4mΩ max
- Working Voltage:** 300 VAC
- Mated Cycles:** 100 Cycles
- RoHS Compliant:** Yes



Mates with:
DPAM



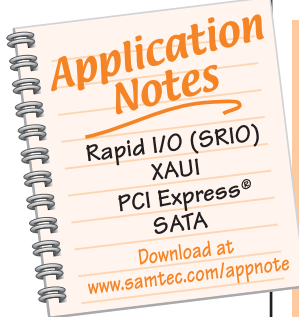
Low Insertion/
Extraction forces



Staggered pitch DPAM/DPAF	Rated @ -3dB Insertion Loss
10mm Stack Height	
Differential Pair Signaling	7.0 GHz / 14.0 Gbps

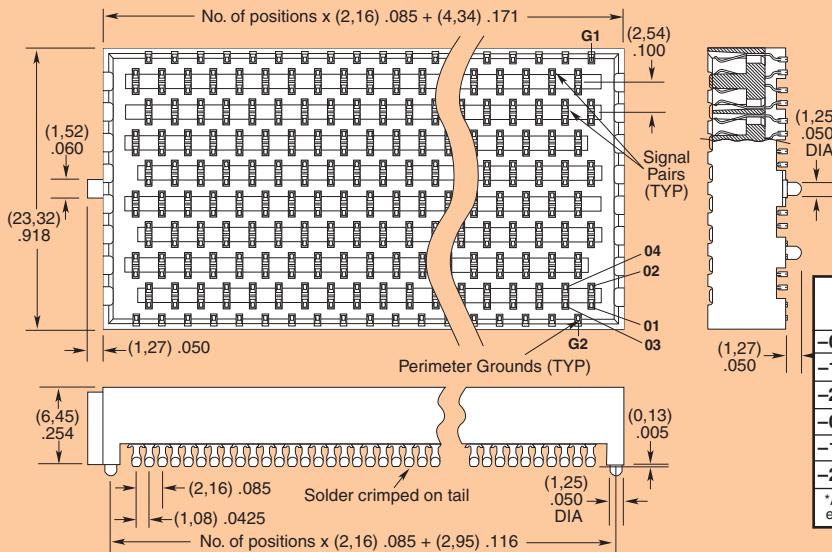
Processing:

- Max Processing Temp:** 230°C for 60 seconds, or 260°C for 20 seconds 3x
- Lead-Free Solderable:** Yes



DPAF	PAIRS PER ROW	03.0	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	OPTION
	-08, -15, -23		-H =30µ" (0,76µm) Gold on contact area, Gold Flash on solder tail	-8 =Eight Pair Rows -3 =Three Pair Rows	-2 = Lead-Free Tin Alloy 96.5% Sn/ 3%Ag/ .5% Cu Solder Crimp		-K =(20,00 mm) 0.80" DIA Polyimide film Pick & Place Pad -TR =Tape & Reel

ALSO AVAILABLE
Tin-Lead Solder Charge.
Call Samtec.



SIZE	USABLE PAIRS PER ARRAY*
-08 x -8	48 Pairs
-15 x -8	104 Pairs
-23 x -8	168 Pairs
-08 x -3	18 Pairs
-15 x -3	39 Pairs
-23 x -3	63 Pairs

*Assumes first and last pair in each row are grounded

Note: Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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